## **STARPOWER**

#### **SEMICONDUCTOR**

## **MOSFET**

## **MD50FFR120C5S**

1200V/50A 6 in one-package

### **General Description**

STARPOWER MOSFET Power Module provides very low  $R_{DS(on)}$  as well as optimized intrinsic diode. It's designed for the applications such as SMPS and DC drives.

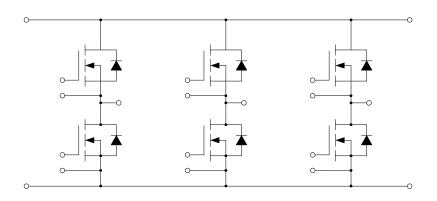
#### **Features**

- SiC power MOSFET
- Low R<sub>DS(on)</sub>
- Optimized intrinsic reverse diode
- Low inductance case avoid oscillations
- Kelvin source terminals for easy drive
- Isolated copper baseplate using AlN DBC technology

### **Typical Applications**

- Main and auxiliary AC drives of electric vehicles
- DC servo and robot drives
- Battery vehicles
- Plasma cutting

### **Equivalent Circuit Schematic**





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**Preliminary** 



# Absolute Maximum Ratings $T_C$ =25°C unless otherwise noted

### **MOSFET**

Symbol	Description	Value	Unit	
$V_{ m DSS}$	Drain-Source Voltage	1200	V	
V <sub>GSS</sub>	Gate-Source Voltage	-4/+22	V	
$I_D$	Drain Current @ T <sub>C</sub> =25°C	73	Α.	
	@ T <sub>C</sub> =100°C	50	A	
$I_{DM}$	Pulsed Drain Current	237	A	
P <sub>D</sub>	Maximum Power Dissipation @ T <sub>i</sub> =150°C	243	W	

### Diode

Symbol	Description	Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage	1200	V
$I_{\mathrm{F}}$	Diode Continuous Forward Current	50	Α
$I_{FM}$	Diode Maximum Forward Current t <sub>p</sub> =1ms	237	A

#### Module

Symbol	<b>Description</b> Val		Unit
T <sub>jmax</sub>	Maximum Junction Temperature	175	°C
$T_{jop}$	Operating Junction Temperature	-40 to +150	°C
$T_{STG}$	Storage Temperature Range	-40 to +125	°C
$V_{\rm ISO}$	Isolation Voltage RMS,f=50Hz,t=1min	2500	V

# $\textbf{MOSFET Characteristics} \ \, T_{C}\!\!=\!\!25^{o}\!C \ \, \text{unless otherwise noted}$

Symbol	Parameter	<b>Test Conditions</b>	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source	$I_D=36A, V_{GS}=18V, T_i=25^{\circ}C$		22.0	37.5	mΩ
	On-Resistance	I <sub>D</sub> =36A,V <sub>GS</sub> =18V, T <sub>i</sub> =150°C		33.0		
$V_{\text{GS(th)}}$	Gate-Source Threshold Voltage	I <sub>D</sub> =18.2mA,V <sub>DS</sub> =10V, T <sub>i</sub> =25°C	2.7		5.6	V
$g_{\mathrm{fs}}$	Forward Transconductance	$V_{DS}$ =20V, $I_{D}$ =36A, $T_{i}$ =25°C		14.2		S
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0V,$ $T_j=25^{\circ}C$			0.1	mA
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0V,$ $T_j=25^{\circ}C$			400	nA
$R_{Gint}$	Internal Gate Resistance			4.0		Ω
$C_{iss}$	Input Capacitance			2.88		nF
$C_{oss}$	Output Capacitance	$V_{GS} = 0V, V_{DS} = 800V,$		0.24		nF
$C_{rss}$	Reverse Transfer Capacitance	f=1.0MHz		0.11		nF
$\overline{Q_{\mathrm{g}}}$	Total Gate Charge			178		nC
$\overline{Q}_{gs}$	Gate-Source Charge	$I_D=36A, V_{DS}=600V, V_{GS}=18V$		40		nC
$Q_{\mathrm{gd}}$	Gate-Drain ("Miller") Charge			80		nC
t <sub>d(on)</sub>	Turn-On Delay Time	$\begin{array}{c} V_{DS}{=}400V, I_{D}{=}18A, \\ R_{G}{=}0\Omega, V_{GS}{=}0/18V, \\ T_{j}{=}25^{\circ}C \end{array}$		29		ns
$t_r$	Rise Time			44		ns
$t_{ m d(off)}$	Turn-Off Delay Time			67		ns
$t_{\rm f}$	Fall Time			28		ns
Eon	Turn-On Switching Loss	V <sub>DS</sub> =600V,I <sub>D</sub> =36A,		0.63		mJ
$E_{\rm off}$	Turn-Off Switching Loss	$R_{G}=0\Omega, V_{GS}=0/18V, T_{j}=25^{\circ}C$		0.24		mJ

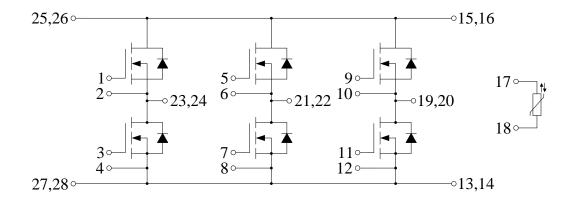
## **Diode Characteristics** $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{\rm F}$	Diode Forward Voltage	$I_F=36A, V_{GE}=0V, T_j=25^{\circ}C$		3.20		V
t <sub>rr</sub>	Diode Reverse Recovery Time	$V_R$ =600V, $I_S$ =36A, di/dt=1100A/ $\mu$ s, $T$ j=25°C		28		ns
$Q_{r}$	Diode Reverse Recovery Charge			175		nC
$I_{rm}$	Peak Reverse Recovery Current			12		A

# Module Characteristics $T_C=25^{\circ}C$ unless otherwise noted

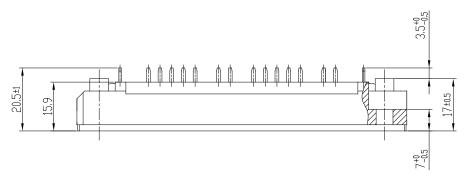
Symbol	Parameter	Min.	Тур.	Max.	Unit	
$R_{thJC}$	Junction-to-Case(per MOSFET)			0.616	K/W	
R <sub>thCH</sub>	Case-to-Heatsink (per MOSFET)		0.120		K/W	
	Case-to-Heatsink (per Module)		0.020			
M	Mounting Torque, Screw M5	3.0		6.0	N.m	
G	Weight of Module		200		g	

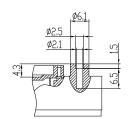
### **Circuit Schematic**

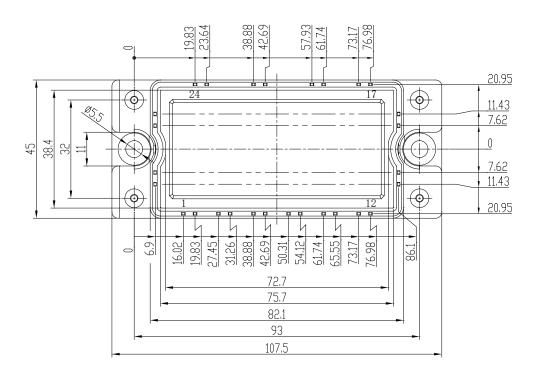


# **Package Dimensions**

#### Dimensions in Millimeters







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